

ABSTRACT OF THE DISCLOSURE

An integrated electronic component includes a ceramic substrate incorporating circuit elements and/or having circuit elements mounted thereon, and a metal case mounted on the ceramic substrate. Notches are formed in substrate-facing segments of the metal case at the positions opposing the corners of the top surface of the ceramic substrate. The notches have a tapered shape having obtuse angles with respect to the top surface of the substrate. The notches may have a substantially circular arc shape. The substrate-facing segments having the notches are seamlessly connected to side segments of the metal case, bent in the vicinity of the notches, and supported by the bent portions in a cantilevered fashion.